2SB1722G

Silicon PNP epitaxial planar type

For high breakdown voltage low-frequency amplification

■ Features

- High collector-emitter voltage (Base open) V_{CEO}
- SS-Mini type package, allowing downsizing of the equipment and automatic insertion through the tape packing

■ Package

- Code
  SSMini3-F3
- Marking Symbol: 4R
- Pin Name
  1. Base
  2. Emitter
  3. Collector

■ Absolute Maximum Ratings $T_a = 25°C$

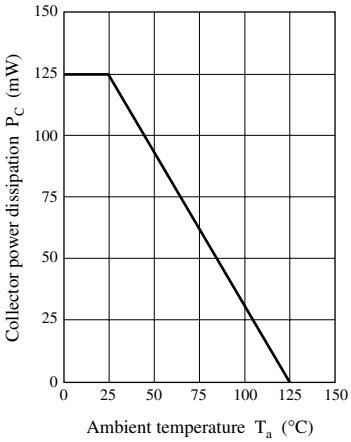
Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V_{CBO}	−100	V
Collector-emitter voltage (Base open)	V_{CEO}	−100	V
Emitter-base voltage (Collector open)	V_{EBO}	−5	V
Collector current	I_C	−20	mA
Peak collector current	I_{CP}	−50	mA
Collector power dissipation	P_C	125	mW
Junction temperature	T_j	125	°C
Storage temperature	T_{stg}	−55 to +125	°C

■ Electrical Characteristics $T_a = 25°C \pm 3°C$

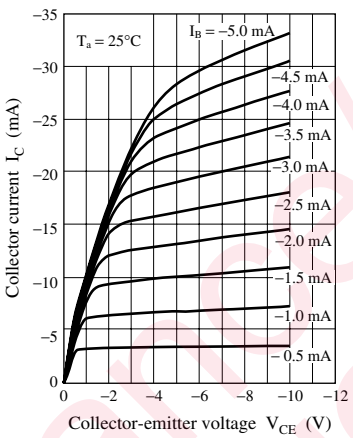
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-base voltage (Emitter open)	V_{CBO}	$I_C = -10$ µA, $I_E = 0$	−100			V
Collector-emitter voltage (Base open)	V_{CEO}	$I_C = -1$ mA, $I_B = 0$	−100			V
Emitter-base voltage (Collector open)	V_{EBO}	$I_E = -10$ µA, $I_C = 0$	−5			V
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = -50$ V, $I_E = 0$			−100	nA
Collector-emitter cut-off current (Base open)	I_{CEO}	$V_{CE} = -50$ V, $I_B = 0$			−1	µA
Forward current transfer ratio	h_{FE}	$V_{CE} = -10$ V, $I_C = -2$ mA	200		700	—
Collector-emitter saturation voltage	$V_{CE(sat)}$	$I_C = -10$ mA, $I_B = -1$ mA			− 0.3	V
Transition frequency	f_T	$V_{CB} = -5$ V, $I_E = 2$ mA, f = 200 MHz		200		MHz

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

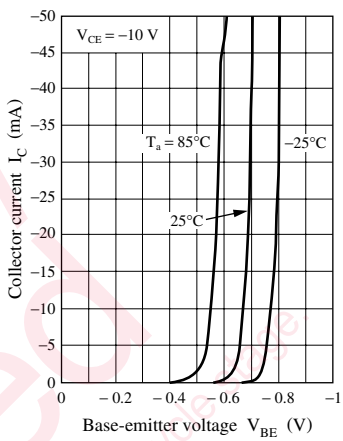
P_C — T_a



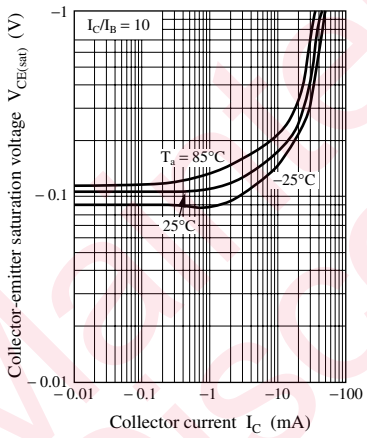
I_C — V_{CE}



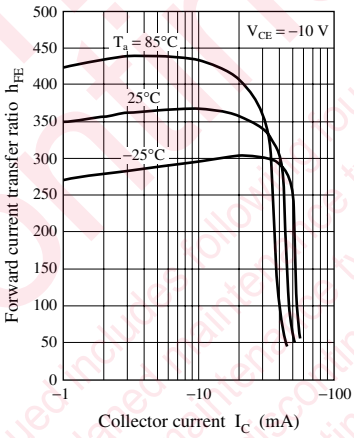
I_C — V_{BE}



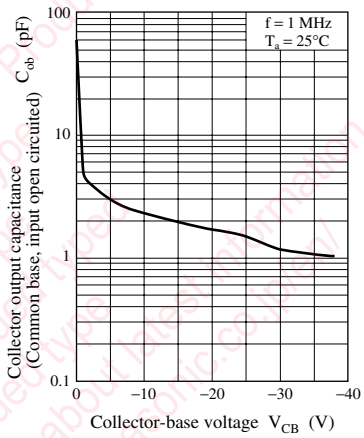
$V_{CE(sat)}$ — I_C



h_{FE} — I_C

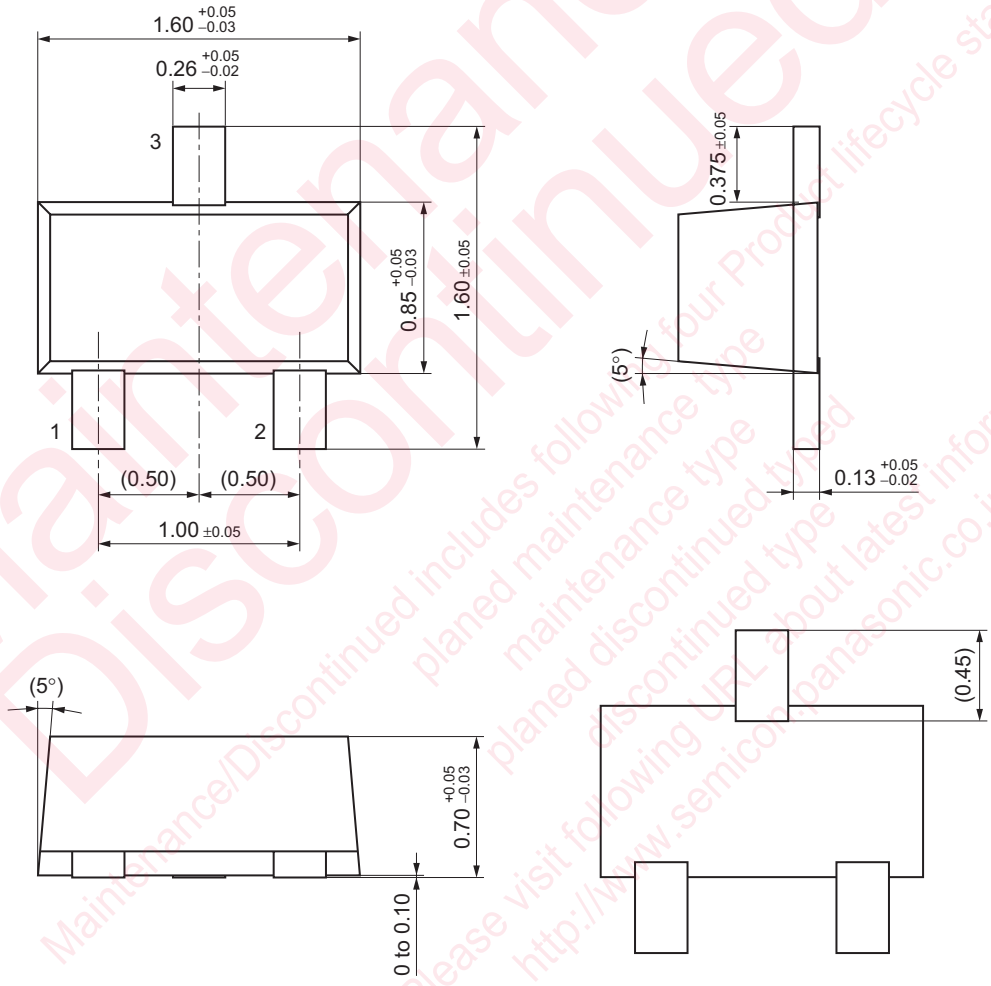


C_{ob} — V_{CB}



SSMini3-F3

Unit: mm



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